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Applicant: Buchwalter *et al.*

Examiner: Clark, Jasmine Jhihan B

Serial No.: 10/039,679

Art Unit: 2815

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**For: CAP ATTACH SURFACE MODIFICATION FOR IMPROVED ADHESION**

Commissioner for Patents  
Washington D.C. 20231

Sir:

This paper is being filed in response to the Office Action Restriction Election Requirement mailed June 12, 2002.

**Preliminary Amendment**

Please amend the above-referenced patent application as follows:

**In The Claims**

Claims 10-29 are currently pending. Claims 28 and 29 have been amended as shown in Appendix A.

10. A method for forming an electronic structure, comprising:

providing a metallic plate;

forming a mineral layer on the metallic plate; and

forming an adhesion promoter layer on the mineral layer.

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